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CMOS Digital Integrated Circuits Silicon Monolithic

## 74HC594D

#### 1. Functional Description

8-Bit Shift Register with Output Register

#### 2. General

The 74HC594D is a high speed 8-BIT SHIFT REGISTER with Output Register fabricated with silicon gate C2MOS technology.

It achieve the high speed operation similar to equivalent LSTTL while maintaining the CMOS low power dissipation.

The 74HC594D contains an 8-bit static shift register which feeds an 8-bit storage register.

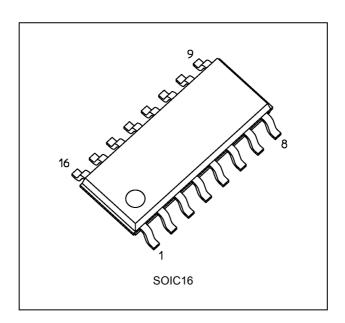
Shift operation is accomplished on the positive going transition of the SCK input. The output register is loaded with the contents of the shift register on the positive going transition of the RCK input. Since RCK and SCK signal are independent, parallel outputs can be held stable during the shift operation. And direct overriding clears (SCLR and RCLR) are provided on both the shift and storage registers.

All inputs are equipped with protection circuits against static discharge or transient excess voltage.

#### 3. Features

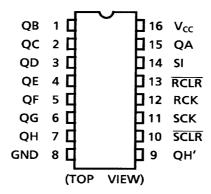
- (1) High speed:  $f_{MAX} = 55 \text{ MHz}$  (typ.) at  $V_{CC} = 5 \text{ V}$
- (2) Low power dissipation:  $I_{CC} = 4.0 \mu A \text{ (max)}$  at  $T_a = 25^{\circ}C$
- (3) Balanced propagation delays: t<sub>PLH</sub> ≈ t<sub>PHL</sub>
- (4) Wide operating voltage range:  $V_{\rm CC(opr)}$  = 2.0 V to 6.0 V

#### 4. Packaging

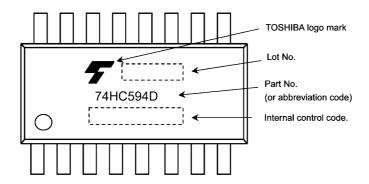




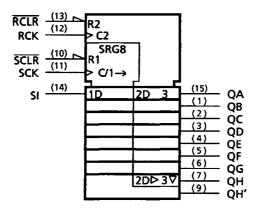
#### 5. Pin Assignment



### 6. Marking



### 7. IEC Logic Symbol



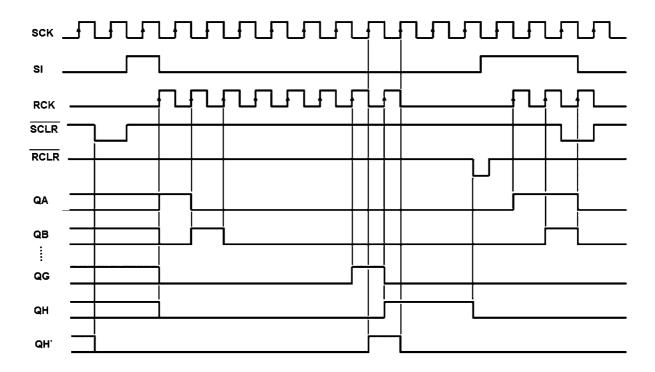


#### 8. Truth Table

	Inputs				Franchism
SI	SCK	SCLR	RCK	RCLR	Function
Х	Х	Х	Х	L	Storage register is cleared.
Х	Х	L	Х	Х	Shift register is cleared.
L		I	X	Х	First stage of S.R. becomes "L". Other stages store the data of previous stage, respectively.
Н		н	Х	Х	First stage of S.R. becomes "H". Other stages store the data of previous stage, respectively.
Х		Н	Х	Х	State of S.R. is not changed.
Х	Х	Х		Н	S.R. data is stored into storage register.
Х	Х	Х		Н	Storage register stage is not changed.

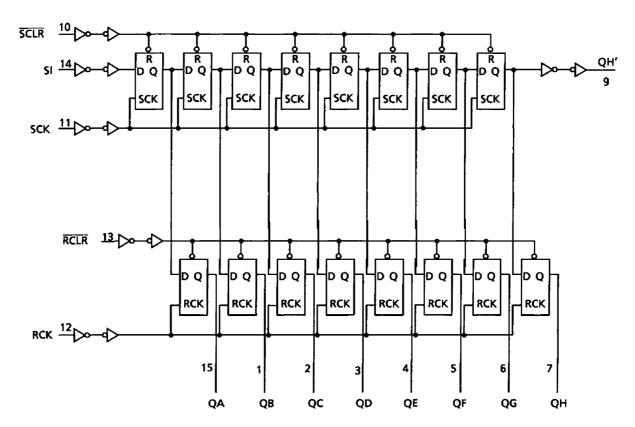
X: Don't care

### 9. Timing Chart





#### 10. System Diagram



#### 11. Absolute Maximum Ratings (Note)

Characteristics	Symbol	Note	Rating	Unit
Supply voltage	V <sub>CC</sub>		-0.5 to 7.0	V
Input voltage	V <sub>IN</sub>		-0.5 to V <sub>CC</sub> + 0.5	V
Output voltage	V <sub>OUT</sub>		-0.5 to V <sub>CC</sub> + 0.5	V
Input diode current	I <sub>IK</sub>		±20	mA
Output diode current	I <sub>OK</sub>		±20	mA
Output current (QH')	I <sub>OUT</sub>		±25	mA
Output current (QA to QH)			±35	
V <sub>CC</sub> /ground current	I <sub>CC</sub>		±75	mA
Power dissipation	P <sub>D</sub>	(Note 1)	500	mW
Storage temperature	T <sub>stg</sub>		-65 to 150	°C

Note: Exceeding any of the absolute maximum ratings, even briefly, lead to deterioration in IC performance or even destruction.

Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings and the operating ranges.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: PD derates linearly with -8 mW/°C above 85 °C



### 12. Operating Ranges (Note)

Characteristics	Symbol	Test Condition	Rating	Unit
Supply voltage	V <sub>CC</sub>	_	2.0 to 6.0	V
Input voltage	V <sub>IN</sub>		0 to V <sub>CC</sub>	V
Output voltage	V <sub>OUT</sub>	_	0 to V <sub>CC</sub>	V
Operating temperature	T <sub>opr</sub>	_	-40 to 125	°C
Input rise and fall times	t <sub>r</sub> ,t <sub>f</sub>	_	0 to 50	μS

Note: The operating ranges must be maintained to ensure the normal operation of the device. Unused inputs must be tied to either  $V_{CC}$  or GND.



#### 13. Electrical Characteristics

## 13.1. DC Characteristics (Unless otherwise specified, $T_a = 25$ °C)

Characteristics	Symbol	Test Condition	١	V <sub>CC</sub> (V)	Min	Тур.	Max	Unit
High-level input voltage	V <sub>IH</sub>	_		2.0	1.50		_	V
				4.5	3.15			
				6.0	4.20			
Low-level input voltage	V <sub>IL</sub>	_		2.0			0.50	V
				4.5			1.35	
				6.0			1.80	
High-level output voltage	V <sub>OH</sub>	$V_{IN} = V_{IH}$ or $V_{IL}$	$I_{OH}$ = -20 $\mu$ A	2.0	1.9	2.0		V
				4.5	4.4	4.5	_	
	]			6.0	5.9	6.0	_	
High-level output voltage			$I_{OH}$ = -4 mA	4.5	4.18	4.31	_	
(QH')			$I_{OH}$ = -5.2 mA	6.0	5.68	5.80	_	
High-level output voltage			$I_{OH}$ = -6 mA	4.5	4.18	4.31	_	
(QA to QH)			$I_{OH} = -7.8 \text{ mA}$	6.0	5.68	5.80	_	
Low-level output voltage	V <sub>OL</sub>	$V_{IN} = V_{IH}$ or $V_{IL}$	$I_{OL}$ = 20 $\mu$ A	2.0	_	0.0	0.1	V
				4.5	_	0.0	0.1	
				6.0	_	0.0	0.1	
Low-level output voltage			$I_{OL}$ = 4 mA	4.5	_	0.17	0.26	
(QH')	]		$I_{OL}$ = 5.2 mA	6.0	_	0.18	0.26	
Low-level output voltage			$I_{OL}$ = 6 mA	4.5	_	0.17	0.26	
(QA to QH)			$I_{OL}$ = 7.8 mA	6.0		0.18	0.26	
Input leakage current	I <sub>IN</sub>	$V_{IN} = V_{CC}$ or GND		6.0	_		±0.1	μА
Quiescent supply current	Icc	$V_{IN} = V_{CC}$ or GND		6.0	_		4.0	μА



## 13.2. DC Characteristics (Unless otherwise specified, T<sub>a</sub> = -40 to 85 °C)

Characteristics	Symbol	Test Conditio	n	V <sub>CC</sub> (V)	Min	Max	Unit
High-level input voltage	V <sub>IH</sub>	_		2.0	1.50	_	V
				4.5	3.15	_	
				6.0	4.20	_	
Low-level input voltage	V <sub>IL</sub>	_		2.0		0.50	V
				4.5		1.35	
				6.0	_	1.80	
High-level output voltage	V <sub>OH</sub>	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OH</sub> = -20 μA	2.0	1.9	_	V
				4.5	4.4	_	
				6.0	5.9	_	
High-level output voltage			I <sub>OH</sub> = -4 mA	4.5	4.13	_	
(QH')			$I_{OH} = -5.2 \text{ mA}$	6.0	5.63	_	
High-level output voltage			$I_{OH}$ = -6 mA	4.5	4.13	_	
(QA to QH)			$I_{OH} = -7.8 \text{ mA}$	6.0	5.63	_	
Low-level output voltage	V <sub>OL</sub>	$V_{IN} = V_{IH}$ or $V_{IL}$	I <sub>OL</sub> = 20 μA	2.0		0.1	V
				4.5		0.1	
				6.0	_	0.1	
Low-level output voltage			I <sub>OL</sub> = 4 mA	4.5	_	0.33	
(QH')			I <sub>OL</sub> = 5.2 mA	6.0	_	0.33	
Low-level output voltage			I <sub>OL</sub> = 6 mA	4.5		0.33	
(QA to QH)			I <sub>OL</sub> = 7.8 mA	6.0		0.33	
Input leakage current	I <sub>IN</sub>	$V_{IN} = V_{CC}$ or GND		6.0	_	±1.0	μА
Quiescent supply current	I <sub>CC</sub>	$V_{IN} = V_{CC}$ or GND		6.0	_	40.0	μА



## 13.3. DC Characteristics (Unless otherwise specified, $T_a$ = -40 to 125 °C)

Characteristics	Symbol	Test Condition	1	V <sub>CC</sub> (V)	Min	Max	Unit
High-level input voltage	V <sub>IH</sub>	_		2.0	1.50	_	V
				4.5	3.15	_	
				6.0	4.20	_	
Low-level input voltage	V <sub>IL</sub>	_		2.0	_	0.50	V
				4.5		1.35	
				6.0	_	1.80	
High-level output voltage	V <sub>OH</sub>	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OH</sub> = -20 μA	2.0	1.9	_	V
				4.5	4.4	_	
				6.0	5.9	_	
High-level output voltage			I <sub>OH</sub> = -4 mA	4.5	3.7	_	
(QH')			I <sub>OH</sub> = -5.2 mA	6.0	5.2	_	
High-level output voltage			I <sub>OH</sub> = -6 mA	4.5	3.7	_	
(QA to QH)			I <sub>OH</sub> = -7.8 mA	6.0	5.2	_	
Low-level output voltage	V <sub>OL</sub>	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OL</sub> = 20 μA	2.0	_	0.1	٧
				4.5	_	0.1	
				6.0	_	0.1	
Low-level output voltage			I <sub>OL</sub> = 4 mA	4.5	_	0.4	
(QH')			I <sub>OL</sub> = 5.2 mA	6.0		0.4	
Low-level output voltage			I <sub>OL</sub> = 6 mA	4.5		0.4	
(QA to QH)			I <sub>OL</sub> = 7.8 mA	6.0		0.4	
3-state output OFF-state leakage current	I <sub>OZ</sub>	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $V_{OUT} = V_{CC} \text{ or GND}$	•	6.0	_	±10.0	μА
Input leakage current	I <sub>IN</sub>	$V_{IN} = V_{CC}$ or GND		6.0	_	±1.0	μА
Quiescent supply current	I <sub>CC</sub>	V <sub>IN</sub> = V <sub>CC</sub> or GND		6.0		160.0	μА



## 13.4. Timing Requirements (Unless otherwise specified, $T_a$ = 25 °C, Input: $t_r$ = $t_f$ = 6 ns)

Characteristics	Symbol	Test Condition	V <sub>CC</sub> (V)	Limit	Unit
Minimum pulse width	$t_{w(L)},t_{w(H)}$	_	2.0	75	ns
(SCK, RCK)			4.5	15	
			6.0	13	]
Minimum pulse width	t <sub>w(L)</sub>	_	2.0	75	ns
(SCLR)			4.5	15	
			6.0	13	]
Minimum setup time	t <sub>S</sub>	_	2.0	50	ns
(SI-SCK)			4.5	10	1
			6.0	9	]
Minimum setup time	t <sub>S</sub>	_	2.0	75	ns
(SCK - RCK)			4.5	15	1
			6.0	13	]
Minimum setup time	t <sub>S</sub>	_	2.0	100	ns
(SCLR -RCK)			4.5	20	
			6.0	17	]
Minimum hold time	t <sub>h</sub>	_	2.0	0	ns
			4.5	0	1
			6.0	0	]
Minimum removal time	t <sub>rem</sub>	_	2.0	50	ns
(SCLR)			4.5	10	1
			6.0	9	]
Clock frequency	f	_	2.0	6	MHz
			4.5	30	]
			6.0	35	]



# 13.5. Timing Requirements (Unless otherwise specified, $T_a = -40$ to 85 °C, Input: $t_r = t_f = 6$ ns)

Characteristics	Symbol	Test Condition	V <sub>CC</sub> (V)	Limit	Unit
Minimum pulse width	$t_{w(L)},t_{w(H)}$	_	2.0	95	ns
(SCK, RCK)			4.5	19	
			6.0	16	
Minimum pulse width	t <sub>w(L)</sub>	_	2.0	95	ns
(SCLR)			4.5	19	
			6.0	16	]
Minimum setup time	t <sub>S</sub>	_	2.0	65	ns
(SI-SCK)			4.5	13	
			6.0	11	]
Minimum setup time	t <sub>S</sub>	_	2.0	95	ns
(SCK - RCK)			4.5	19	
			6.0	16	]
Minimum setup time	t <sub>S</sub>	_	2.0	125	ns
(SCLR -RCK)			4.5	25	]
			6.0	21	]
Minimum hold time	t <sub>h</sub>	_	2.0	0	ns
			4.5	0	1
			6.0	0	]
Minimum removal time	t <sub>rem</sub>	_	2.0	65	ns
(SCLR)			4.5	13	1
			6.0	11	]
Clock frequency	f	_	2.0	5	MHz
			4.5	25	]
			6.0	28	]



# 13.6. Timing Requirements (Unless otherwise specified, $T_a$ = -40 to 125 °C, Input: $t_f$ = $t_f$ = 6 ns)

Characteristics	Symbol	Test Condition	V <sub>CC</sub> (V)	Limit	Unit
Minimum pulse width	$t_{w(L)}, t_{w(H)}$	_	2.0	115	ns
(SCK, RCK)			4.5	23	
			6.0	20	]
Minimum pulse width	t <sub>w(L)</sub>	_	2.0	115	ns
(SCLR)			4.5	23	
			6.0	20	]
Minimum setup time	t <sub>S</sub>	_	2.0	75	ns
(SI-SCK)			4.5	15	
			6.0	13	]
Minimum setup time	t <sub>S</sub>	_	2.0	115	ns
(SCK - RCK)			4.5	23	
			6.0	20	1
Minimum setup time	t <sub>S</sub>	_	2.0	150	ns
(SCLR -RCK)			4.5	30	
			6.0	26	1
Minimum hold time	t <sub>h</sub>	_	2.0	0	ns
			4.5	0	
			6.0	0	]
Minimum removal time	t <sub>rem</sub>	_	2.0	75	ns
(SCLR)			4.5	15	
			6.0	13	]
Clock frequency	f	_	2.0	4	MHz
			4.5	20	]
			6.0	24	]

# 13.7. AC Characteristics (Unless otherwise specified, $C_L$ = 15 pF, $V_{CC}$ = 5 V, $T_a$ = 25 °C, Input: $t_r$ = $t_f$ = 6 ns)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Output transition time (QH')	t <sub>TLH</sub> ,t <sub>THL</sub>	_	_	4	8	ns
Propagation delay time (SCK-QH')	t <sub>PLH</sub> ,t <sub>PHL</sub>	_	_	12	21	
Propagation delay time(SCLR-QH')	t <sub>PHL</sub>	_	_	15	30	
Maximum clock frequency	f <sub>MAX</sub>	_	35	55	_	MHz



## 13.8. AC Characteristics (Unless otherwise specified, $T_a$ = 25 °C, Input: $t_r$ = $t_f$ = 6 ns)

Characteristics	Symbol	Note	Test Condition	C <sub>L</sub> (pF)	V <sub>CC</sub> (V)	Min	Тур.	Max	Unit
Output transition time	t <sub>TLH</sub> ,t <sub>THL</sub>		_	50	2.0	1	25	60	ns
(Qn)					4.5	ı	7	12	
					6.0	ı	6	10	
Output transition time	t <sub>TLH</sub> ,t <sub>THL</sub>		_	50	2.0	ı	30	75	ns
(QH')					4.5	ı	8	15	
					6.0	ı	7	13	
Propagation delay time	t <sub>PLH</sub> ,t <sub>PHL</sub>		_	50	2.0	_	45	125	ns
(SCK-QH')					4.5	_	15	25	
					6.0		13	21	
Propagation delay time	t <sub>PHL</sub>		_	50	2.0	_	60	175	ns
(SCLR -QH')					4.5	_	18	35	
					6.0	_	15	30	
Propagation delay time (RCK-Qn)	t <sub>PLH</sub> ,t <sub>PHL</sub>		_	50	2.0	_	60	150	ns
					4.5	_	20	30	
					6.0	1	17	26	
				150	2.0	_	75	190	
					4.5	_	25	38	
					6.0	1	22	32	
Output enable time	t <sub>PZL</sub> ,t <sub>PZH</sub>		$R_L = 1 k\Omega$	50	2.0	_	45	135	ns
					4.5	_	15	27	
					6.0	_	13	23	
				150	2.0	_	60	175	
					4.5	_	20	35	
					6.0		17	30	1
Output disable time	$t_{PLZ}, t_{PHZ}$		$R_L = 1 k\Omega$	50	2.0	_	30	150	ns
					4.5		15	30	1 <b> </b>
					6.0		14	26	
Maximum clock frequency	f <sub>MAX</sub>		_	50	2.0	6	17	_	MHz
					4.5	30	50	_	
					6.0	35	59	_	
Input capacitance	C <sub>IN</sub>		_			_	3	_	pF
Power dissipation capacitance	C <sub>PD</sub>	(Note 1)	_			_	41	_	pF

Note 1:  $C_{PD}$  is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation.  $I_{CC(opr)} = C_{PD} \times V_{CC} \times f_{|N} + I_{CC}$ 



# 13.9. AC Characteristics (Unless otherwise specified, $T_a$ = -40 to 85 °C, Input: $t_r$ = $t_f$ = 6 ns)

Characteristics	Symbol	Test Condition	C <sub>L</sub> (pF)	V <sub>CC</sub> (V)	Min	Max	Unit
Output transition time	t <sub>TLH</sub> ,t <sub>THL</sub>	_	50	2.0	_	75	ns
(Qn)				4.5	_	15	
				6.0	_	13	]
Output transition time	t <sub>TLH</sub> ,t <sub>THL</sub>	_	50	2.0	_	95	ns
(QH')				4.5	_	19	
				6.0	_	16	
Propagation delay time	t <sub>PLH</sub> ,t <sub>PHL</sub>	_	50	2.0	_	155	ns
(SCK-QH')				4.5	_	31	
				6.0	_	26	
Propagation delay time	t <sub>PHL</sub>	_	50	2.0	_	220	ns
(SCLR -QH')				4.5	_	44	
				6.0	_	37	
Propagation delay time	t <sub>PLH</sub> ,t <sub>PHL</sub>	_	50	2.0	_	190	ns
(RCK-Qn)				4.5	_	38	
				6.0	_	32	]
			150	2.0	_	240	
				4.5	_	48	
				6.0	_	41	
Output enable time	t <sub>PZL</sub> ,t <sub>PZH</sub>	$R_L = 1 k\Omega$	50	2.0	_	170	ns
				4.5	_	34	
				6.0	_	29	
			150	2.0	_	220	
				4.5	_	44	1
				6.0	_	37	
Output disable time	t <sub>PLZ</sub> ,t <sub>PHZ</sub>	$R_L = 1 k\Omega$	50	2.0	_	190	ns
				4.5	_	38	
				6.0	_	33	
Maximum clock frequency	f <sub>MAX</sub>	_	50	2.0	5	_	MHz
				4.5	25	_	]
				6.0	28	_	



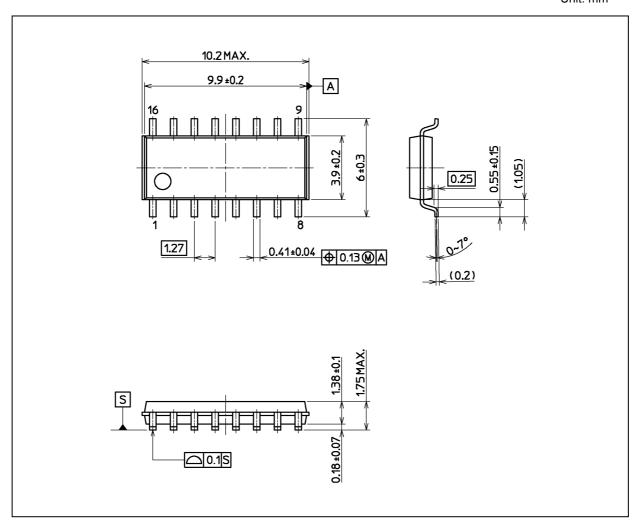
# 13.10. AC Characteristics (Unless otherwise specified, $T_a$ = -40 to 125 °C, Input: $t_f$ = $t_f$ = 6 ns)

Characteristics	Symbol	Test Condition	C <sub>L</sub> (pF)	V <sub>CC</sub> (V)	Min	Max	Unit
Output transition time (Qn)	t <sub>TLH</sub> ,t <sub>THL</sub>	_	50	2.0	_	90	ns
				4.5	_	18	
				6.0	_	15	
Output transition time (QH')	t <sub>TLH</sub> ,t <sub>THL</sub>	_	50	2.0	_	115	ns
				4.5	_	23	
				6.0	_	20	
Propagation delay time (SCK-QH')	t <sub>PLH</sub> ,t <sub>PHL</sub>	_	50	2.0	_	190	ns
				4.5	_	38	
				6.0	_	32	
Propagation delay time (SCLR -QH')	t <sub>PHL</sub>	_	50	2.0	_	265	ns
				4.5	_	53	
				6.0	_	45	
Propagation delay time (RCK-Qn)	t <sub>РLН</sub> ,t <sub>РНС</sub>	_	50	2.0	_	225	ns
				4.5	_	45	
				6.0	_	38	
			150	2.0	_	285	
				4.5	_	57	
				6.0	_	48	
Output enable time	t <sub>PZL</sub> ,t <sub>PZH</sub>	R <sub>L</sub> = 1 kΩ	50	2.0	_	205	ns
				4.5	_	41	
				6.0	_	35	
			150	2.0	_	265	
				4.5	_	53	
				6.0	_	45	
Output disable time	t <sub>PLZ</sub> ,t <sub>PHZ</sub>	$R_L = 1 \text{ k}\Omega$	50	2.0	_	225	ns
				4.5	_	45	
				6.0	_	38	
Maximum clock frequency	f <sub>MAX</sub>	_	50	2.0	4	_	MHz
				4.5	20	_	
				6.0	24	_	1



### **Package Dimensions**

Unit: mm



Weight: 0.15 g (typ.)

	Package Name(s)
Nickname: SOIC16	



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